Dual Buffer with Open Drain Outputs

The NL27WZ07 is a high performance dual buffer with open drain outputs operating from a 1.65 to 5.5 V supply.

The internal circuit is composed of multiple stages, including an open drain output. The open drain output provides the capability to set the output switching level to a user selectable value with an external resistor and power supply. The logic high output value is set by the external power supply and can be less than, equal or greater than the V_{CC} power supply, provided the voltage supply is less than 5.5 V.

Features

- Extremely High Speed: t_{PD} 2.3 ns (typical) at V_{CC} = 5 V
- Designed for 1.65 V to 5.5 V V_{CC} Operation, CMOS compatible
- Over Voltage Tolerant Inputs
- LVTTL Compatible Interface Capability with 5 V TTL Logic with V_{CC} = 3 V
- LVCMOS Compatible
- 24 mA Output Sink Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Chip Complexity: FET = 72; Equivalent Gate = 18
- Pb-Free Packages are Available



Figure 1. Pinout (Top View)







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= Pb-Free Package

(Note: Microdot may be in either location) *Date Code orientation and/or position may vary depending upon manufacturing location.

PIN ASSIGNMENT

1	IN A1
2	GND
3	IN A2
4	OUT Y2
5	V _{CC}
6	OUT Y1

FUNCTION TABLE

A Input	Y Output
L	L
н	Z

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol	Characte	eristics	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		$-0.5 \leq V_I \leq +7.0$	V
Vo	DC Output Voltage	Output in Z or LOW State (Note 1)	$-0.5 \le V_O \le 7.0$	V
Ι _{ΙΚ}	DC Input Diode Current	-50	mA	
I _{OK}	DC Output Diode Current	-50	mA	
Ι _Ο	DC Output Sink Current	±50	mA	
I _{CC}	DC Supply Current per Supply Pin	±100	mA	
I _{GND}	DC Ground Current per Ground Pin	±100	mA	
T _{STG}	Storage Temperature Range		-65 to +150	°C
PD	Power Dissipation in Still Air	SC-88, TSOP-6	200	mW
θ_{JA}	Thermal Resistance	SC-88, TSOP-6	333	°C/W
ΤL	Lead Temperature, 1 mm from case for 10	S	260	°C
Τ _J	Junction Temperature under Bias		+ 150	°C
I _{Latchup}	Latchup Performance Abov	ve V _{CC} and Below GND at 85°C (Note 5)	± 500	mA
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Classification	Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	> 2000 > 200 N/A	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability. 1. I_O absolute maximum rating must be observed.

Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.
 Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.
 Tested to JESD22-C101-A

5. Tested to EIA/JESD78

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V _{CC}	Supply Voltage	Operating Data Retention Only	1.65 1.5	5.5 5.5	V
VI	Input Voltage		0	5.5	V
Vo	Output Voltage	(Z or LOW State)	0	5.5	V
T _A	Operating Free-Air Temperature		-55	+125	°C
$\Delta t / \Delta V$	Input Transition Rise or Fall Rate		0 0 0	20 10 5	ns/V

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	Τį	∠ = 25°	C	–55°C ≤T ₄	λ ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V _{IH}	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V _{CC} 0.75 V _{CC}			0.75 V _{CC} 0.75 V _{CC}		V
V _{IL}	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.3 V _{CC} 0.3 V _{CC}		0.3 V _{CC} 0.3 V _{CC}	V
I _{LKG}	Z-State Output Leakage Current	V _{IN} = V _{IL} V _{OUT} = V _{CC} or GND	2.3 to 5.5			±5.0		±10.0	μΑ
V _{OL}	Low-Level Output Voltage	I _{OL} = 100 μA	1.65 to 5.5		0.0	0.1		0.1	V
	$V_{IN} = V_{IL}$	I _{OL} = 4 mA	1.65		0.08	0.24		0.24	
		I _{OL} = 8 mA	2.3		0.20	0.3		0.3	
		I _{OL} = 12 mA	2.7		0.22	0.4		0.4	
		I _{OL} = 16 mA	3.0		0.28	0.4		0.4	
		I _{OL} = 24 mA	3.0		0.38	0.55		0.55	
		I _{OL} = 32 mA	4.5		0.42	0.55		0.55	
I _{IN}	Input Leakage Current	V_{IN} or $V_{OUT} = V_{CC}$ or GND	0 to 5.5			±0.1		±1.0	μΑ
I _{OFF}	Power Off–Output Leakage Current	V _{OUT} = 5.5 V	0			1		10	μΑ
I _{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1		10	μA

AC ELECTRICAL CHARACTERISTICS t_R = t_F = 2.5 ns; C_L = 50 pF; R_L = 500 Ω

				T _A = 25°C		0	–55°C ≤T	_A ≤ 125°C			
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit		
t _{PZL}	Propagation Delay $R_{L=}$ R_1 = 5000 Ω, C_L = 15 pF		1.8 ± 0.15	1.8	5.3	11.5	1.8	12.0	ns		
	(Figure 3 and 4)		2.5 ± 0.2	1.2	3.7	5.8	1.2	6.4			
		$R_{L=} R_{1}$ = 500 Ω, C_{L} = 50 pF		$R_{L} = R_1 = 500 \Omega, C_L = 50 pF$	3.3 ± 0.3	0.8	2.9	4.4	0.8	4.8	
				0.5	2.3	3.5	0.5	3.9			
t _{PLZ}	Propagation Delay	$R_{L=} R_{1}$ = 5000 Ω , C_{L} = 15 pF	1.8 ± 0.15	1.8	5.3	11.5	1.8	12.0	ns		
	(Figure 3 and 4)		2.5 ± 0.2	1.2	2.8	5.8	1.2	6.4			
		$R_{L =} R_1 = 500 \Omega, C_L = 50 pF$	3.3 ± 0.3	0.8	2.1	4.4	0.8	4.8			
			5.0 ± 0.5	0.5	1.4	3.5	0.5	3.9			

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	2.5	pF
C _{OUT}	Output Capacitance	V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	4.0	pF
C _{PD}	Power Dissipation Capacitance (Note 6)	10 MHz, V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	4.0	pF

6. C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no-load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.







 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 4. Test Circuit

ORDERING INFORMATION

Device	Package	Shipping [†]
NL27WZ07DFT2	SC-88 / SOT-363 / SC-70	
NL27WZ07DFT2G	SC-88 / SOT-363 / SC-70 (Pb-Free)	3000 / Tape & Reel
NL27WZ07DTT1	TSOP-6 / SOT-23 / SC-59	
NL27WZ07DTT1G	TSOP-6 / SOT-23 / SC-59 (Pb-Free)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SC-88/SC70-6/SOT-363 CASE 419B-02 ISSUE W



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 419B-01 OBSOLETE, NEW STANDARD 419B-02.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.95	1.10	0.031	0.037	0.043	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A3		0.20 REF			0.008 RE	ΞF	
b	0.10	0.21	0.30	0.004	0.008	0.012	
С	0.10	0.14	0.25	0.004	0.005	0.010	
D	1.80	2.00	2.20	0.070	0.078	0.086	
Е	1.15	1.25	1.35	0.045	0.049	0.053	
е		0.65 BSC			0.026 BSC		
L	0.10	0.20	0.30	0.004	0.008	0.012	
HE	2.00	2.10	2.20	0.078	0.082	0.086	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSOP-6 CASE 318G-02 ISSUE T



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14 5M 1982

- ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- DIMENSIONS A AND B DO NOT INCLUDE
 MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.90	1.00	1.10	0.035	0.039	0.043	
A1	0.01	0.06	0.10	0.001	0.002	0.004	
b	0.25	0.38	0.50	0.010	0.014	0.020	
С	0.10	0.18	0.26	0.004	0.007	0.010	
D	2.90	3.00	3.10	0.114	0.118	0.122	
Е	1.30	1.50	1.70	0.051	0.059	0.067	
е	0.85	0.95	1.05	0.034	0.037	0.041	
L	0.20	0.40	0.60	0.008	0.016	0.024	
HE	2.50	2.75	3.00	0.099	0.108	0.118	
θ	0°	-	10°	0°	-	10°	

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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